
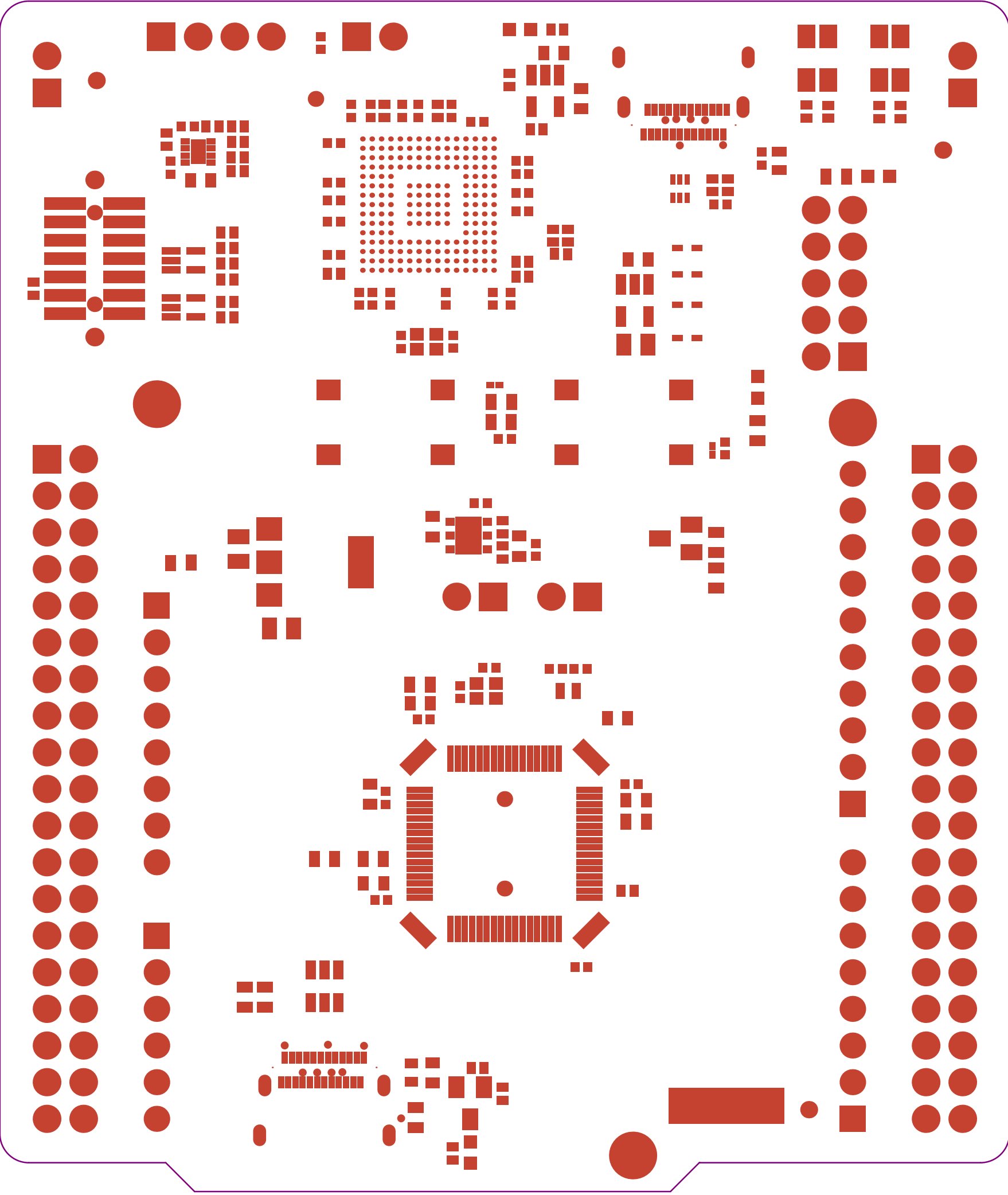

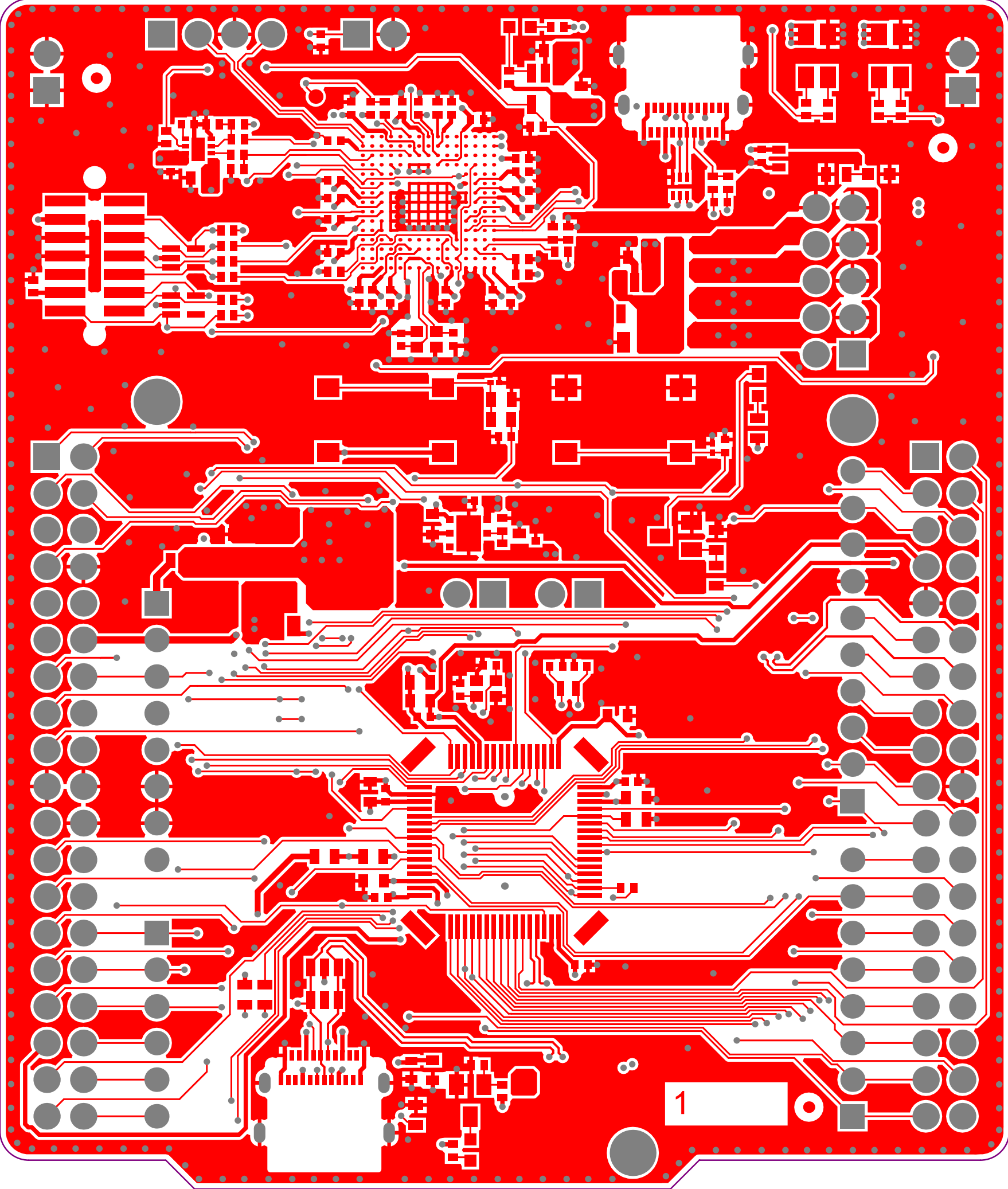



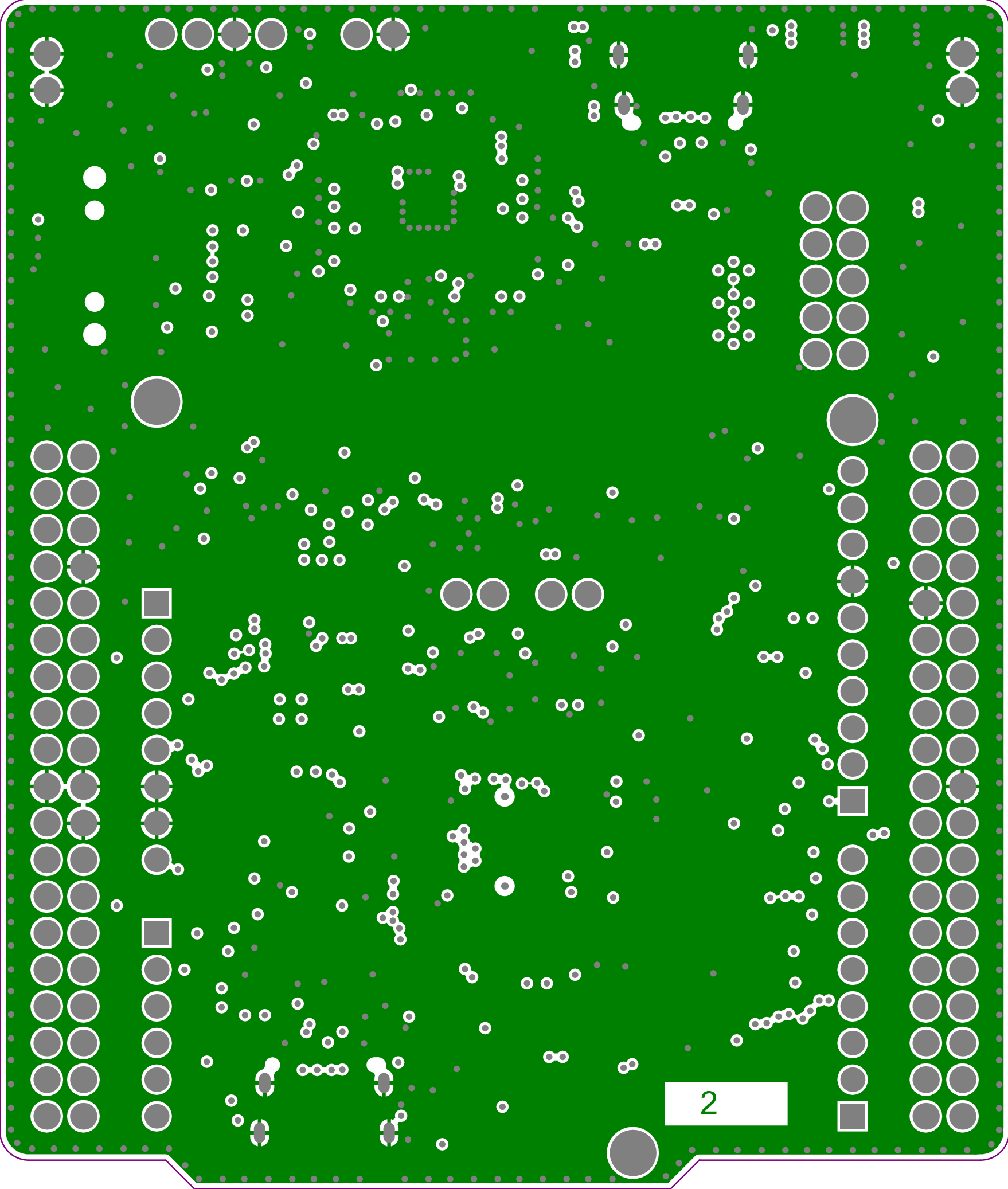
Project: NUCLEO-64		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	MB1814	
Date: 07 Mar 2023	Rev: C	




Project: NUCLEO-64		
Layer: <b>Top Solder</b>	Gerber: <b>.GTS</b>	
Variant: [No Variations]	MB1814	
Date: 07 Mar 2023	Rev: C	

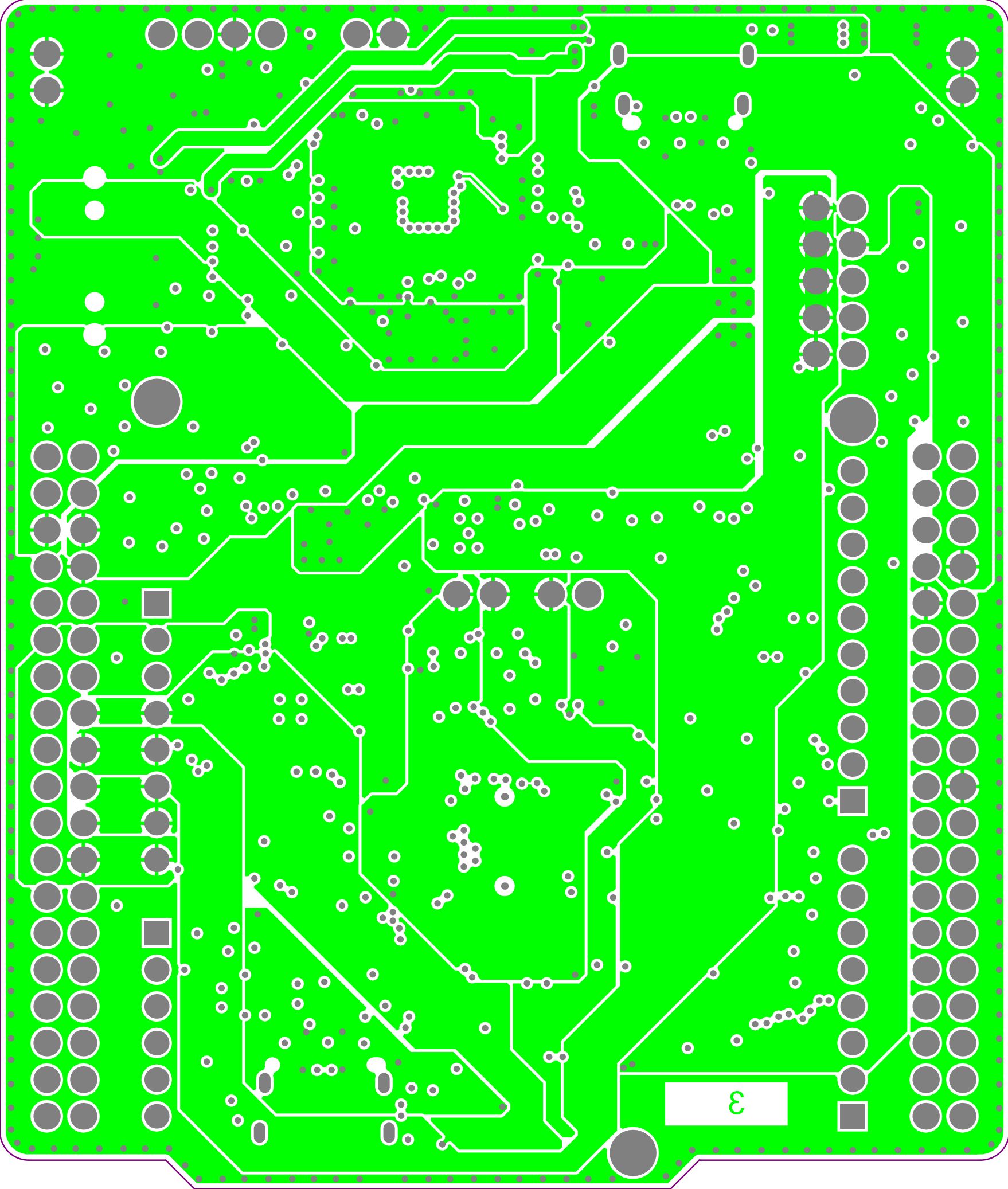



Project: NUCLEO-64		
Layer: <b>Top Layer</b>	Gerber: <b>.GTL</b>	
Variant: [No Variations]	MB1814	
Date: 07 Mar 2023	Rev: C	

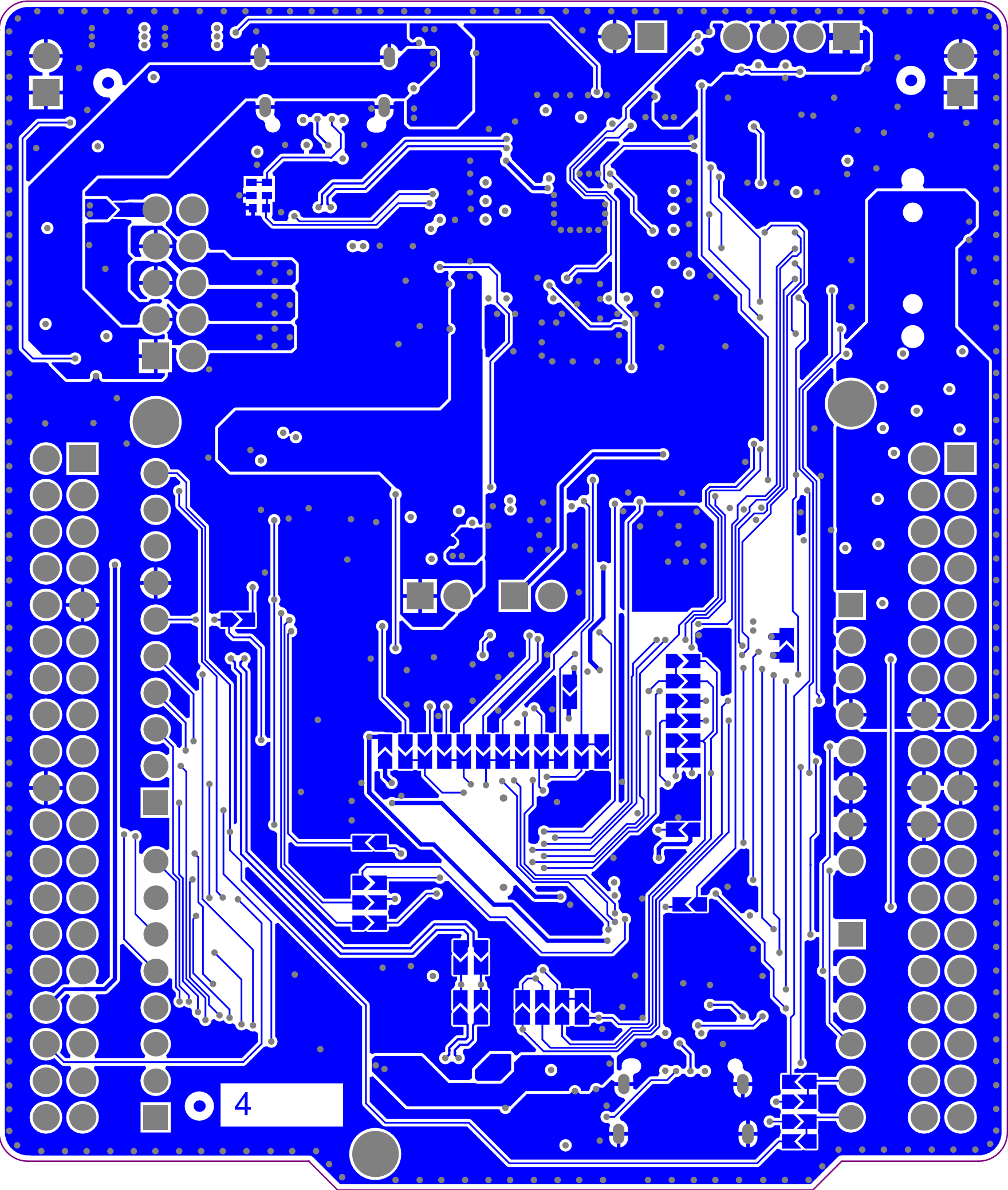



Project: NUCLEO-64		
Layer: Signal Layer 1	Gerber: .G1	
Variant: [No Variations]	MB1814	
Date: 07 Mar 2023	Rev: C	

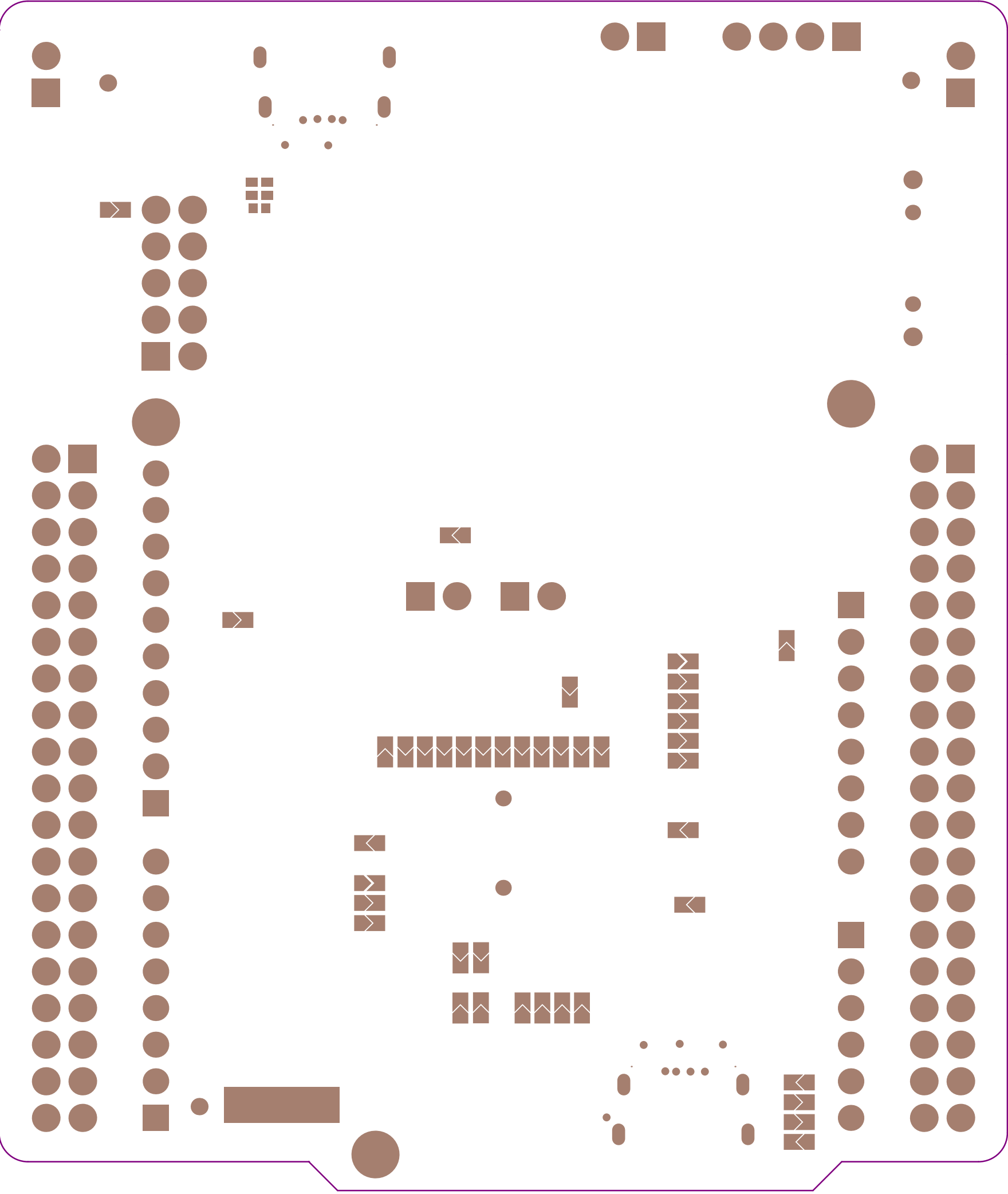





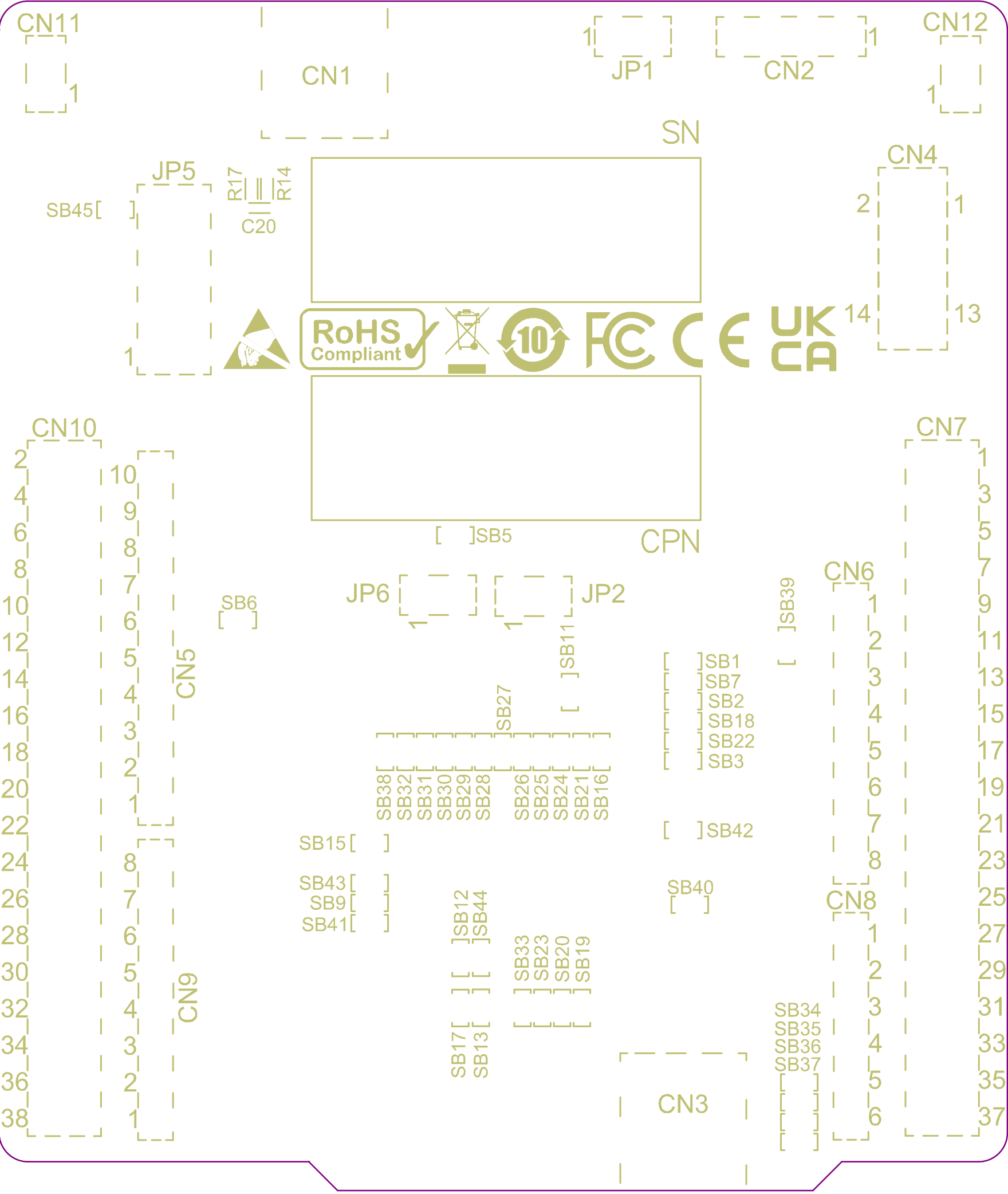
Project: NUCLEO-64		
Layer: Signal Layer 2	Gerber: .G2	
Variant: [No Variations]	MB1814	
Date: 07 Mar 2023	Rev: C	




Project: NUCLEO-64		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	MB1814	
Date: 07 Mar 2023	Rev: C	



Project: NUCLEO-64		
Layer: Bottom Solder	Gerber: .GBS	
Variant: [No Variations]	MB1814	
Date: 07 Mar 2023	Rev: C	



Project: NUCLEO-64		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	MB1814	
Date: 07 Mar 2023	Rev: C	



« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE  
WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »

PCB SPECIFICATIONS :

A. MATERIAL : FR-4 ☐ TG-170 ☒ TG-150 ☐ TG-140

B. MATERIAL FAMILY : N/A

C. SOLDERMASK COLOR : ☐ GREEN ☒ WHITE ☐ RED ☐ BLACK

D. SILKSCREEN COLOR : ☐ WHITE ☐ YELLOW ☐ BLACK ☒ Blue ink PANTONE 2955

E. SURFACE FINISH : ☒ ENIG ☐ IMMERSION SILVER ☐ IMMERSION TIN

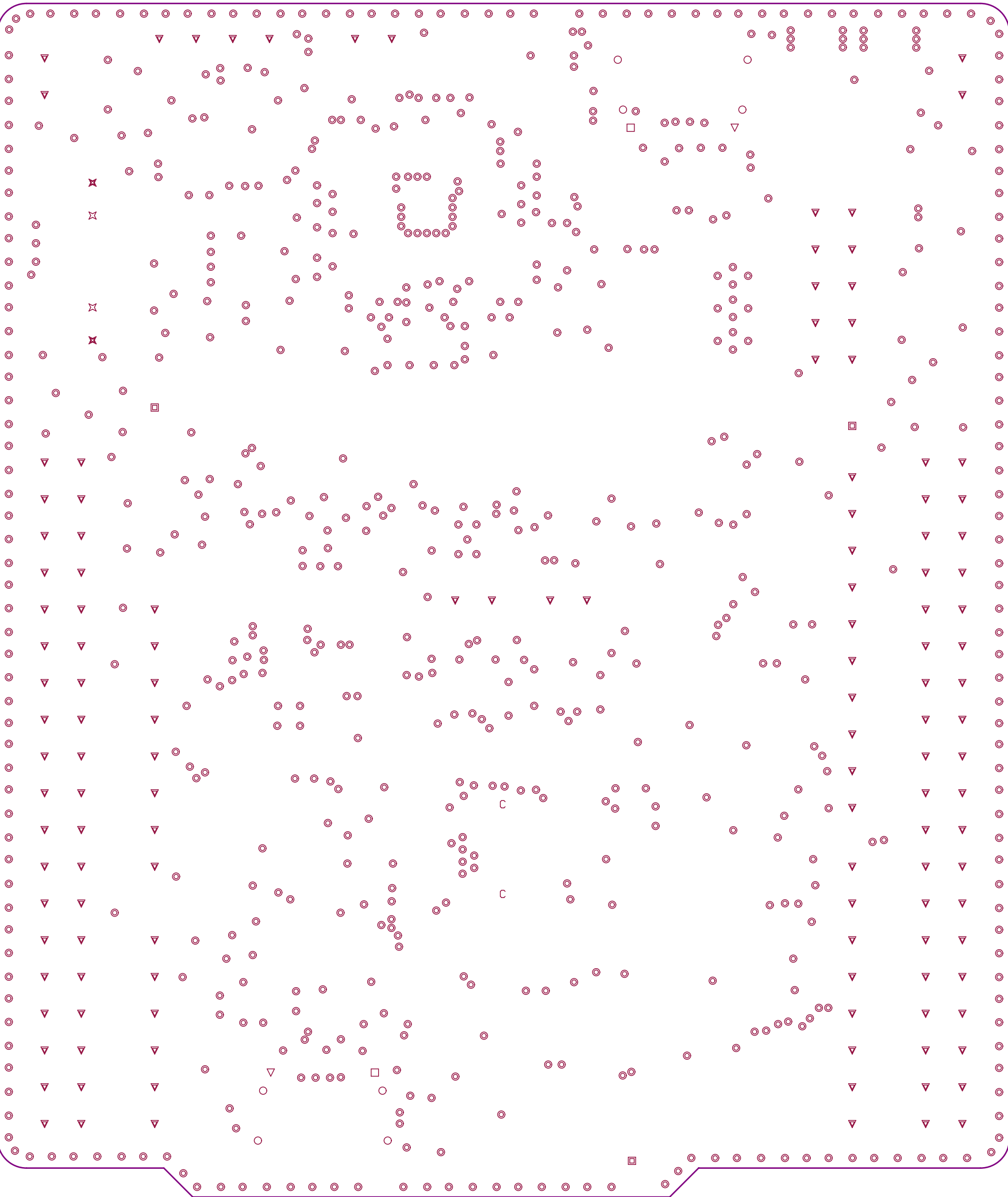
☐ HASL ☐ HASL (PB-FREE) ☐ GOLDEN FINGER

☐ IMPEDANCE CONTROL : ☐ NO ☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA : PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.  
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

☐ STACK-UP : SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

\*\*Plating type :  
lead Gold



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,015mm	3.5	
1	Top Layer		0,042mm		
	Dielectric 1	PP-IT-180A	0,106mm	4.2	
2	Signal Layer 1		0,035mm		
	Dielectric 2	FR4	1,248mm	4.2	
3	Signal Layer 2		0,035mm		
	Dielectric 3	PP-IT-180A	0,106mm	4.2	
4	Bottom Layer		0,042mm		
	Bottom Solder	Solder Resist	0,015mm	3.5	
	Bottom Overlay				

PCB : TYPE 3


ASPECT-RATIO, AXE Z :  
6:1 to 8:1  
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT  
TRACKS : 0.120mm  
GAPS : 0.120mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length	Routed Path Length
⊙	710	0,200mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-	-
○	8	0,500mm (19,69mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	1,100mm (43,31mil)	0,600mm (23,62mil)
▽	2	0,650mm (25,59mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
□	2	0,650mm (25,59mil)	NPTH	Slot	Top Layer - Bottom Layer	Pad	0,950mm (37,40mil)	0,300mm (11,81mil)
✕	2	0,970mm (38,19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
C	2	1,000mm (39,37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
▽	132	1,000mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
✕	2	1,190mm (46,85mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
◻	3	3,200mm (125,98mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
	863 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Project: NUCLEO-64		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	MB1814	
Date: 07 Mar 2023	Rev: C	